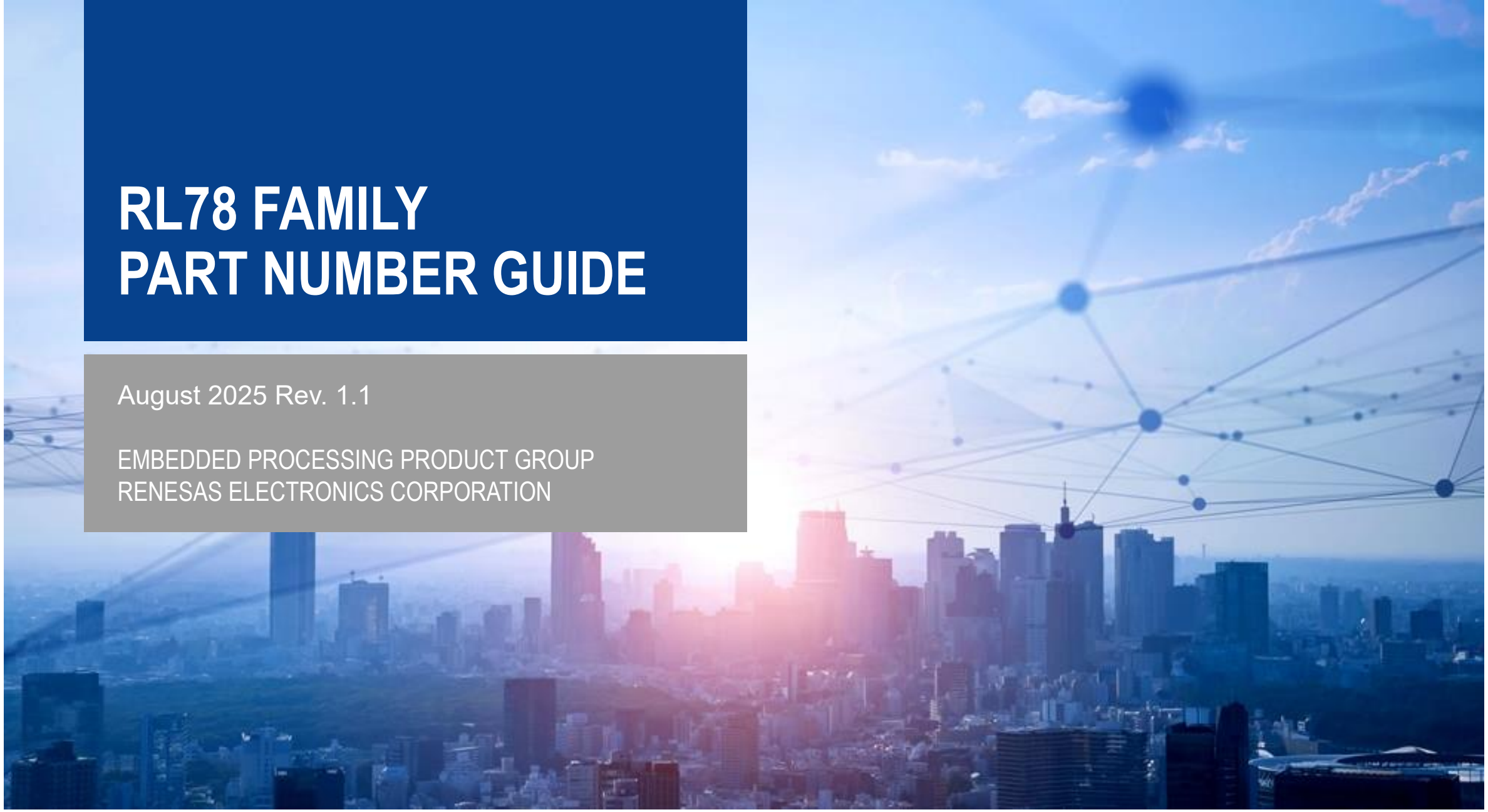
RL78 FAMILY
PART NUMBER GUIDE

August 2025 Rev. 1.1

EMBEDDED PROCESSING PRODUCT GROUP
RENESAS ELECTRONICS CORPORATION



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RL78:EXPLANATION OF ORDERABLE PART NUMBERS

(For part numbers start with R5F1)

R5 F 1 00 6 E C A SP #Vx

- R5: Renesas MCU
- F: ROM Type F: Flash
- 1: RL78 Family
- 00: Product group
- 6: Pin count
- E: ROM Size (KB)
- C: Bonding wire (Only part of RL78/F1x)*2
- A: Temperature &Quality Grade
- SP: Package, Pin Pitch
- #Vx: Packaging, Material (Pb-free)

Product group

00	G13 with DF	0K	G1C USB Peri	1C	I1E
01	G13 no DF	0M	I1B	1E	G1G
02	G12 with DF	0N	I1C with AES	1F	G1H
03	G12 no DF	0P	F14	1M	L1A
04	G14	0R	L12	1N	H1D with AFE
05	G11	0T	D1A with CAN 100pinQFP/256KB	1P	H1D with AFE
07	I1A			1R	H1D no AFE
09	F12	0W	L13	1T	I1C no AES
0A	F13 no CAN	0Y	G10	1W	G1M
0B	F13 with CAN	10	L1C with USB	1Y	G1N
0C	D1A no CAN	11	L1C no USB	1Z	G1P
0D	D1A with CAN	13	F15	20	G15
0E	G1A	17	I1D	21	G16
0F	G1E	1A	G1D	40	G13A
0J	G1C USBHost	1B	G1F		

Pin count

0	8	E	40
1	10	F	44
4	16	G	48
6	20	J	52
7	24	L	64
8	25	M	80
9	28	N	85
A	30	P	100
B	32	S	128
C	36	T	144
D	38		

ROM Size (KB)

4	1	D	48
6	2	E	64
7	4	F	96
8	8	G	128
9	12	H	192
A	16	J	256
B	24	K	384
C	32	L	512

Temperature &Quality Grade

A	-40°C to 85°C	Consumer
D	-40°C to 85°C	Industrial
G	-40°C to 105°C	Industrial
M	-40°C to 125°C	Industrial
J	-40°C to 85°C	Automotive
L	-40°C to 105°C	Automotive
K	-40°C to 125°C	Automotive
Y	-40°C to 150°C	Automotive

Bonding wire (Only part of RL78/F1x)*2

C	Cu (Copper)

Package, Pin Pitch

SP	SSOP 0.65 mm	NS	WDFN 0.65mm
	LSSOP 0.65 mm	LA	WFLGA 0.5 mm
SM	TSSOP 0.65 mm		VFLGA 0.65 mm
SN	SOP 1.27 mm	BG	VFBGA 0.4 mm
NA	HWQFN 0.5 mm		TFBGA 0.5mm
	HVQFN 0.5 mm	FA	LQFP 0.65 mm
NB	HWQFN 0.65 mm	FB	LFQFP 0.5 mm
	HWQFN 0.4 mm	FP	LQFP 0.8 mm

Packaging, Material (Pb-free)

#0	Full Carton (HWQFN,HVQFN,WFLGA)
#1	Full Carton (SSOP,LSSOP,LQFP,LFQFP,TSSOP,WDFN)
#U, #2	Tray (HWQFN,HVQFN,VFBGA,VFLGA,WFLGA,FLGA,TFBGA)
#V, #3	Tray, Tube*1 (SSOP,LSSOP,LQFP,LFQFP,TSSOP,WDFN)
#W, #4	Embossed Tape (SSOP(Only for F13,F14,F15)) (HWQFN,HVQFN,VFBGA,VFLGA,WFLGA,FLGA,TFBGA)
#X, #5	Embossed Tape (SSOP,LSSOP,LQFP,LFQFP,TSSOP,WDFN)
#6	Full Tray (HWQFN,HVQFN,VFBGA,WFLGA)
#7	Full Tray (LFQFP,LQFP,SSOP,TSSOP,LSSOP,WDFN)
#H, #G	Full Carton (SSOP,QFP,QFN) (Only for RL78/F1x,D1A)

*1: For 20-pin RL78/G11, RL78/G12, RL78/G15, RL78/G16 RL78/I1A and RL78/I1D LSSOP products only the package specification is tube.

*2: Please contact Renesas sales or agent for details.

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RL78:EXPLANATION OF ORDERABLE PART NUMBERS

(For part numbers start with R7F1)

R7 F 1 00G L J 3 C FB -C #AAx

- R7: Renesas MCU
- F: ROM Type F: Flash
- 1: RL78 Family
- 00G: Product group
- L: Pin count
- J: ROM Size (KB)
- 3: Temperature
- C: Quality Grade
- FB: Package, Pin Pitch
- -C: Bonding wire (Only part of RL78/F2x)
- #AAx: Packaging, Material (Pb-free)

00G	G23	**23F**	F23
01G	G24	**24F**	F24
02G	G22		
00L	L23		

Pin count

4	16	**F**	44
6	20	**G**	48
7	24	**J**	52
8	25	**L**	64
A	30	**M**	80
B	32	**P**	100
C	36	**S**	128
E	40		

ROM Size (KB)

C	32
E	64
F	96
G	128
H	192
J	256
K	384
L	512
N	768

Temperature

2	-40℃ to 85℃
3	-40℃ to 105℃
4	-40℃ to 125℃
5	-40℃ to 150℃

Quality Grade

A	Automotive
C	Industrial
D	Consumer

Package, Pin Pitch

SP	LSSOP 0.65 mm
FP	LQFP 0.8 mm
FA	LQFP 0.65 mm
FB	LFQFP 0.5 mm
NP	HWQFN 0.5 mm
LA	WFLGA 0.5 mm
BG	VFBGA 0.4 mm

Bonding wire (Only part of RL78/F2x)

C	Cu (Copper)

Packaging, Material (Pb-free)

#AA	Tray (LFQFP, LQFP, LSSOP, HWQFN)
#AC	Tray (WFLGA)
#BA	Full Carton (LFQFP, LQFP, LSSOP, HWQFN)
#BC	Full Carton (WFLGA)
#UA	Full Tray (LFQFP, LQFP, LSSOP, HWQFN)
#UC	Full Tray (WFLGA)
#CA	Tube* (LSSOP) * Also known as “magazine”(shipping form is the same)
#HA	Embossed Tape (LFQFP, LQFP, LSSOP, HWQFN)
#HC	Embossed Tape (WFLGA)

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